

REMARKS

The above amendment corrects an obvious omission in new claim 12.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

Claim 12 has been amended as follows:

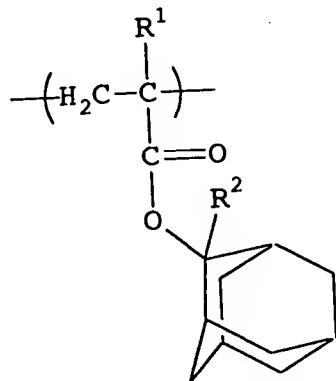
12. (Amended) A positive-working photoresist composition which comprises, as a uniform solution in an organic solvent:

(A) 100 parts by weight of a resinous compound capable of being imparted with increased solubility in an aqueous alkaline solution by interaction with an acid;

(B) from 0.5 to 30 parts by weight of a radiation-sensitive acid generating compound capable of generating an acid by irradiation with a radiation; and

(C) an organic solvent in an amount sufficient to dissolve the components (A) and (B), the component (A) being a copolymer consisting of the monomeric units of

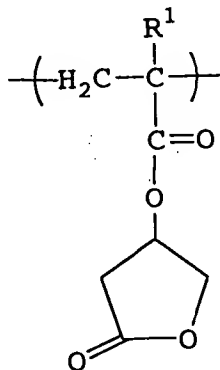
(a1) from 30 to 60% by moles of 2-alkyl-2-adamantyl (meth) acrylate units having the formula:



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in which R¹ is a hydrogen atom or a methyl group and R² is an alkyl group having 1 to 4 carbon atoms.

(a2) from 20 to 50% by moles of 2-oxooxapentyl (meth) acrylate units having the formula:



in which R¹ is a hydrogen atom or a methyl group.

(a3) from 20 to 40% by moles of 1-hydroxyadamantyl (meth) acrylate units.